

from the group consisting of thermoset and thermoplastic polymers overlying said compliant layer and defining said second surface of said dielectric element.

<sup>6</sup>~~66~~. A chip assembly as claimed in claim <sup>4</sup>~~64~~, wherein said compliant layer is formed from an elastomeric material.

<sup>7</sup>~~67~~. A chip assembly as claimed in claim <sup>4</sup>~~64~~, wherein said compliant layer is formed from a compressible foam.

Sub B3> 68. A chip assembly as claimed in claim 61, wherein said dielectric element includes a sheet-like, electrically conductive grounding layer disposed between said central terminals and said chip.

69. A ~~chip~~ assembly as claimed in claim 61, wherein some of said central terminals are disposed adjacent the edge bounding said hole.

70. A chip assembly as claimed in claim 61, wherein said plurality of central terminals are disposed at said second surface of said dielectric element. --

**In the Title:**

Please amend the title of the application to: -- Semiconductor Chip Package With Center Contacts. --

**In the Specification:**

Page 1, before line 1, insert -- This is a divisional of United States Patent

08/861,280 filed May 21, 1997 which is in turn a continuation of United States Patent

Application 08/319,966, filed on October 7, 1994, <sup>now patent no. 5,685, 685</sup> which is in turn a continuation of

United States Patent Application 08/030,194, filed April 28, 1993, <sup>now patent no. 5,679, 977</sup> as the national

phase of International Application PCTUS/91/06920 filed September 24, 1991. Said

030,194 Application in turn is a continuation of United States Patent Application

07/765,928, filed September 24, 1991 now United States Patent 5,347,159. Said